



# **PNP Darlington High Power Silicon Transistor**

Qualified per MIL-PRF-19500/623

## DESCRIPTION

This high power PNP transistor is rated at 12 amps and is military qualified up to the JANTXV level for high reliability applications. This TO-254AA low-profile design offers flexible mounting options.

**FEATURES** 

Important: For the latest information, visit our website http://www.microsemi.com.

#### • JEDEC registered 2N7371.

- JAN, JANTX, and JANTXV qualifications are available per MIL-PRF-19500/623. (See <u>part nomenclature</u> for all available options.)
- RoHS compliant versions available (commercial grade only).

#### **APPLICATIONS / BENEFITS**

- High power operation.
- Flexible, low-profile TO-254AA package

#### **MAXIMUM RATINGS** @ $T_c = +25$ °C unless otherwise noted.

Parameters/Test Conditions	Symbol	Value	Unit
Junction and Storage Temperature	$T_{\rm J}$ and $T_{\rm STG}$	-65 to +200	°C
Thermal Resistance Junction-to-Case	Rejc	1.5	°C/W
Collector-Base Voltage	V <sub>CBO</sub>	-100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5.0	V
Total Power Dissipation (see Figure 1)	Pτ	100	W
Base Current	Ι <sub>Β</sub>	-0.2	А
Collector Current	Ι <sub>C</sub>	-12	А

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<u>Qualified Levels:</u> JAN, JANTX, and JANTXV



## **TO-254AA Package**

T4-LDS-0318, Rev. 1 (9/16/13)



## **MECHANICAL and PACKAGING**

- CASE: Nickel plated CRS steel
- TERMINALS: Ceramic feed-though, hot solder dip, Ni plated Alloy 52, copper core. RoHS compliant pure tin dip is available for commercial versions only.
- MARKING: Part number, date code, and polarity symbol
- POLARITY: See Schematic on last page
- WEIGHT: Approximately 6.5 grams
- See <u>Package Dimensions</u> on last page.

#### PART NOMENCLATURE



SYMBOLS & DEFINITIONS				
Symbol	Definition			
Ι <sub>Β</sub>	Base current: The value of the dc current into the base terminal.			
Ι <sub>C</sub>	Collector current: The value of the dc current into the collector terminal.			
Ι <sub>Ε</sub>	Emitter current: The value of the dc current into the emitter terminal.			
Tc	Case temperature: The temperature measured at a specified location on the case of a device.			
V <sub>CB</sub>	Collector-base voltage: The dc voltage between the collector and the base.			
V <sub>CBO</sub>	Collector-base voltage, base open: The voltage between the collector and base terminals when the emitter terminal is open-circuited.			
Vcc	Collector-supply voltage: The supply voltage applied to a circuit connected to the collector.			
V <sub>CE</sub>	Collector-emitter voltage: The dc voltage between the collector and the emitter.			
V <sub>CEO</sub>	Collector-emitter voltage, base open: The voltage between the collector and the emitter terminals when the base terminal is open-circuited.			
V <sub>EB</sub>	Emitter-base voltage: The dc voltage between the emitter and the base			
V <sub>EBO</sub>	Emitter-base voltage, collector open: The voltage between the emitter and base terminals with the collector terminal open-circuited.			



ELECTRICAL CHARACTERISTICS $@T_{c} = +$	+25 °C unless otherwise noted
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Characteristics	Symbol	Min.	Max.	Unit
OFF CHARACTERISTICS				
Collector-Emitter Breakdown Voltage $I_{C} = -100 \text{ mA}$	V <sub>(BR)CEO</sub>	-100		V
Collector-Emitter Cutoff Current $V_{CE} = -50 V$	I <sub>CEO</sub>		-1.0	mA
Collector-Emitter Cutoff Current $V_{CE} = -100 \text{ V}, \text{ V}_{BE} = 1.5 \text{ V}$ $V_{CE} = -100 \text{ V}, \text{ V}_{BE} = 1.5 \text{ V}, \text{ T}_{A} = +150 ^{\circ}\text{C}$	I <sub>CEX</sub>		-20 -1.0	μA mA
Emitter-Base Cutoff Current $V_{EB} = -5.0 V$	I <sub>EBO</sub>		-2.0	mA

## **ON CHARACTERISTICS**

Forward-Current Transfer Ratio $I_{C} = -6.0 \text{ A}, V_{CE} = -3.0 \text{ V}$ $I_{C} = -12.0 \text{ A}, V_{CE} = -3.0 \text{ V}$	h <sub>FE</sub>	1,000	18,000	
$I_{C} = -6.0 \text{ A}, V_{CE} = -3.0 \text{ V}, T_{A} = +150 \text{ °C}$		300		
Collector-Emitter Saturation Voltage				
I <sub>C</sub> = -12 A, I <sub>B</sub> = -120 mA	V <sub>CE(sat)</sub>		-3.0	V
Base-Emitter Saturation Voltage $I_{C} = -12 \text{ A}, I_{B} = -120 \text{ mA}$	V <sub>BE(sat)</sub>		-4.0	V

## **DYNAMIC CHARACTERISTICS**

Magnitude of Common Emitter Small-Signal Short-Circuit				
Forward Current Transfer Ratio	lh. I	40	050	
$I_{C} = -5 \text{ A}, V_{CE} = -3.0 \text{ V}, \text{ f} = 1 \text{ MHz}$	l'ife	10	250	



#### **ELECTRICAL CHARACTERISTICS** @ $T_c = 25$ °C unless otherwise noted. (continued)

#### SWITCHING CHARACTERISTICS

Turn-On Time			
$V_{CC}$ = -30 V, $I_{C}$ = -12 A; $I_{B1}$ = -120 mA	t <sub>on</sub>	2.0	μS
Turn-Off Time			
$V_{CC} = -30 \text{ V}, I_{C} = -12 \text{ A}; I_{B1} = I_{B2} = -120 \text{ mA}$	t <sub>off</sub>	10	μs

#### SAFE OPERATING AREA (See figure below and <u>MIL-STD-750,Test Method 3053</u>)

DC Tests T<sub>C</sub> = +25 °C, t ≥ 1 second, 1 Cycle Test 1 V<sub>CE</sub> = -8.3 V, I<sub>C</sub> = -12 A Test 2 V<sub>CE</sub> = -30 V, I<sub>C</sub> = -3.3 A Test 3 V<sub>CE</sub> = -90 V, I<sub>C</sub> = -150 mA

\* Pulse test: Pulse width 300  $\mu$ sec, duty cycle  $\leq$  2%.



## Safe Operating Area



## GRAPHS



FIGURE 1 Temperature-Power Derating Graph

#### NOTES:

- All devices are capable of operating at ≤ T<sub>J</sub> specified on this curve. Any parallel line to this curve will intersect the appropriate power for the desired maximum T<sub>J</sub> allowed.
- Derate design curve constrained by the maximum junction temperature (T<sub>J</sub> ≤ +200°C) and power rating specified. (See <u>Maximum</u> <u>Ratings</u>.)
- 3. Derate design curve chosen at  $T_J \le +150^{\circ}$ C, where the maximum temperature of electrical test is performed.
- 4. Derate design curves chosen at  $T_J \le +125^{\circ}$ C, and  $+110^{\circ}$ C to show power rating where most users want to limit  $T_J$  in their application.



**GRAPHS** (continued)



FIGURE 2 Thermal Impedance Graph



#### PACKAGE DIMENSIONS



	Dimensions				
Ltr	Inch		Millimeters		
	Min	Max	Min	Max	
BL	0.535	0.545	13.59	13.84	
СН	0.249	0.260	6.32	6.60	
LD	0.035	0.045	0.89	1.14	
LL	0.510	0.570	12.95	14.48	
LO	0.150	50 BSC 3.81 BSC			
LS	0.150	BSC	SC 3.81 BSC		
MHD	0.139	0.149	3.53 3.78		
МНО	0.665	0.685	16.89 17.40		
TL	0.790	0.800	20.07 20.32		
TT	0.040	0.050	1.02 1.27		
TW	0.535	0.545	13.59	13.84	
Term 1	Base				
Term 2	Collector				
Term 3	Emitter				

#### NOTES:

- 1. Dimensions are in inches. Millimeters are given for information only.
- 2. All terminals are isolated from case.
- 3. Protrusion of ceramic eyelets included in dimension LL.
- 4. In accordance with ASME Y14.5M, diameters are equivalent to  $\Phi x$  symbology.

## SCHEMATIC

